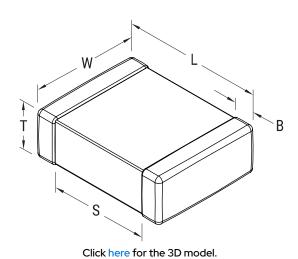




SMD Comm X8G HT150C, Ceramic, 2,700 pF, 1%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	67 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions		
Chip Size	1812	
L	4.5mm +/-0.3mm	
W	3.2mm +/-0.3mm	
Т	1mm +/-0.10mm	
S	2.3mm MIN	
В	0.6mm +/-0.35mm	

VV	3.2111111 +/ -0.3111111
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm
Packaging Specifications	

Packaging

Specifications		
Capacitance	2,700 pF	
Measurement Condition	1 kHz 1.0Vrms	
Tolerance	1%	
Voltage DC	250 VDC	
Dielectric Withstanding Voltage	625 VDC	
Temperature Range	-55/+150°C	
Temp. Coefficient	X8G	
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms	
Dissipation Factor	0.1% 1 kHz 1.0Vrms	
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours	
Insulation Resistance	100 GOhms	

		Applied (TCC)
Packaging Quantity	4000	Dissipation Factor
		Aging Rate

T&R, 330mm, Plastic Tape

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